

FL2010
No Clean Liquid Flux

Product Description

FL2010 provides matte solder joints and excellent solderability, with reduction in micro-solderballing and solder bridging at connectors and QFP. The residue left behind is non-tacky, non-corrosive and non-conductive.

Application

FL2010 is specially formulated for spraying, foaming as well as dipping (Cu substrate) processes. Recommended onboard preheat temperature is 80–120°C (for heavy double sided board and boards running with pallet, the onboard preheat temperature may increase 10–20°C).

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

Recommended Solvent

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, FL2010 can be stored for up to 6 months. FL2010 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging

Available in 18kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Transparent yellow
Specific Gravity @ 25°C	0.807 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 1hr)	9.50 +/- 0.5 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	Not added
<small>JIS Z 3197 8.1.4.2.1</small>	
Acid Value Test	45.5 +/- 2.0 mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4.1</small>	
Water Extract Resistivity	> 1 x 10 ⁴ Ω-cm
<small>JIS Z 3197 8.1.1</small>	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 ⁸ Ω, Pass
<small>IPC-TM-650 2.6.3.3</small>	
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
<small>IPC-TM-650 2.6.14.1</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
Copper Mirror Test	Classified as "L", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ROLO
<small>IPC J-STD-004</small>	
Spread Factor	> 70% (SnCu0.7&SCS7)
<small>JIS Z 3197 8.3.1.1</small>	
Residue Dryness Test	Dry
<small>IPC-TM-650 2.4.47</small>	
<small>JIS Z 3197 8.5.1</small>	
Surface Finish	Matte (SCS7)

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